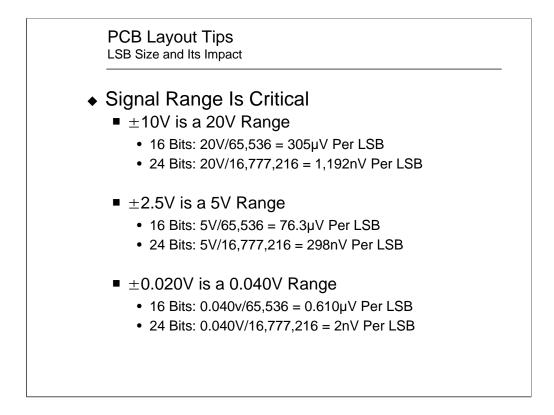


Layout of printed circuit boards (PCBs) could be an all-day discussion. Rather than give you a set of rules to follow, which almost always have exceptions, we'll look here at some general principles and then review a number of actual board layouts that illustrate common mistakes.

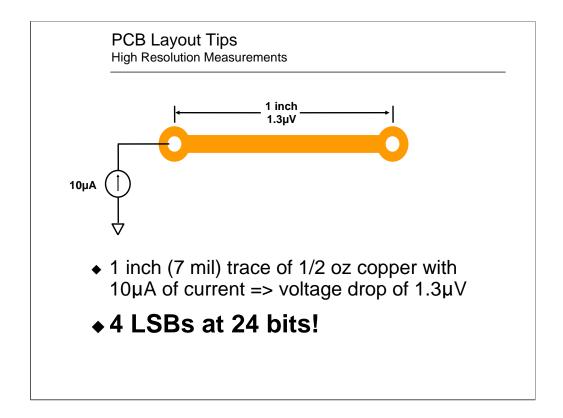
PCB Layout Tips

♦ LSB size

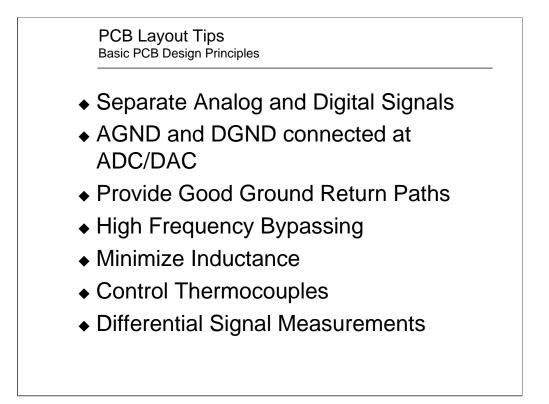
- Impact on layout decisions
- Basic PCB Design Principles
  - For High Resolution
- PCB Layout Reviews
  - Learn from the misfortune of others!



Where  $\pm 10V$  gives you an LSB of  $305\mu V$ , a 5V signal only gives you 76.2 $\mu V$  for a 16-bit LSB. When gain is added into the system, the resolution can sink into the noise.

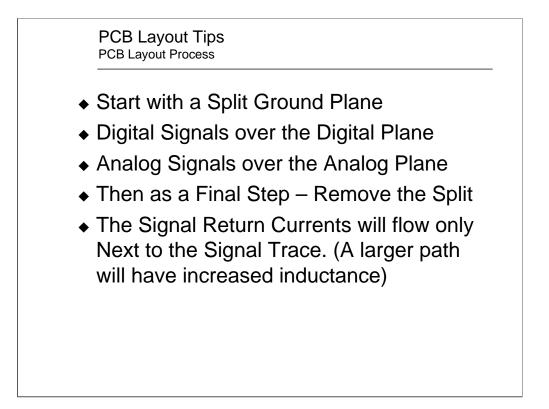


You must be careful with the PCB layout for a 12-bit design. For a 16-bit design you have to do everything correctly to achieve that performance; it should be obvious that a 24-bit design will be affected by any errors in the layout.

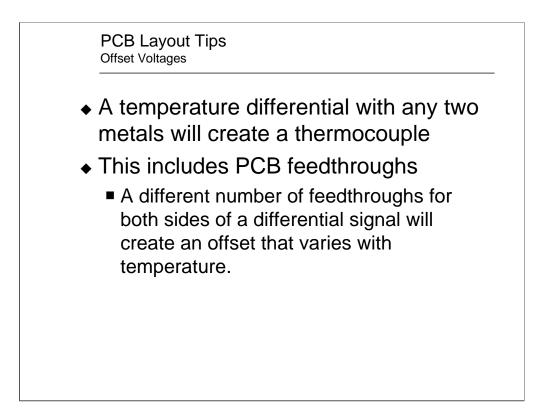


The separation of the Analog and Digital section of the PCB keeps noisy digital from the low level analog. However, they must come together at the ADC or DAC. It is important that the Analog Ground and the Digital Ground be connected together at the ADC or DAC. This allows a quick return for the ground currents as the analog and digital portions of the device communicate.

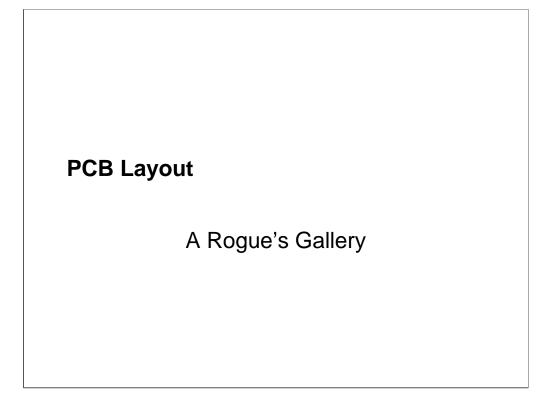
Inductance is determined by the size of the loop of current. Providing a path for return currents next to the signal trace will reduce the inductance. That is the advantage of a solid ground plane. If a reasonably solid plane can't be achieved with two layers, then more layers should be used.



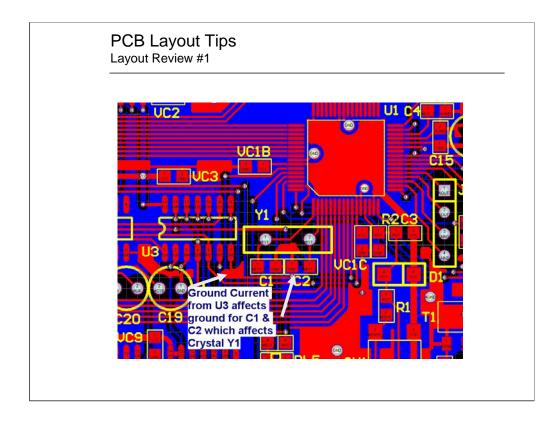
Since AGND and DGND are connected at the ADC/DAC and also at the power supply, there is a ground loop created. By having a solid ground plane this can be eliminated. The analog signals will still just flow in the analog portions of the ground plane and the digital signals will only flow in the digital portion of the ground plane. The reason why they will not travel throughout the board, is because a larger path has a larger inductance. The signals will travel through the path of lowest impedance.



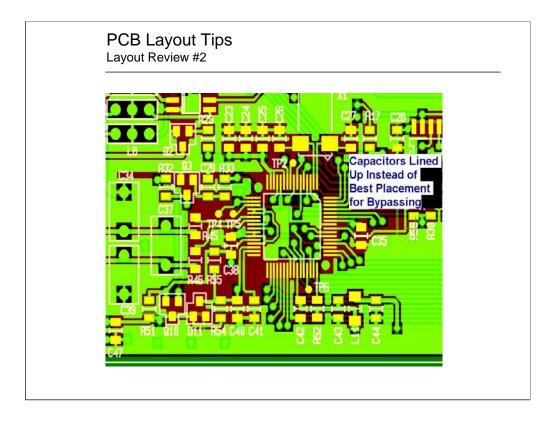
Your board design can create additional offset voltages because of the traces and feedthroughs. To minimize offset it is good to route the signal traces differentially next to each other so that they will see the same thermal gradients and the same number of feedthroughs.



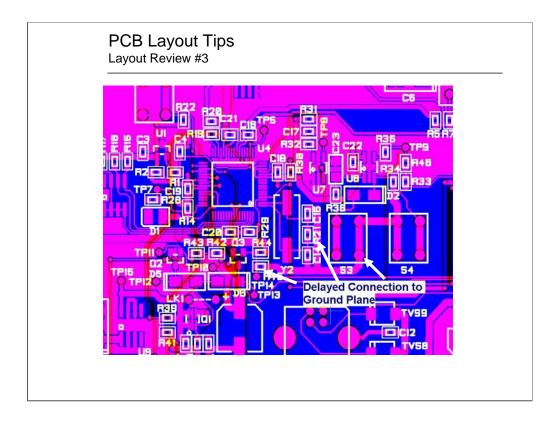
We'll now look at a few examples of circuit layouts that make some common mistakes.



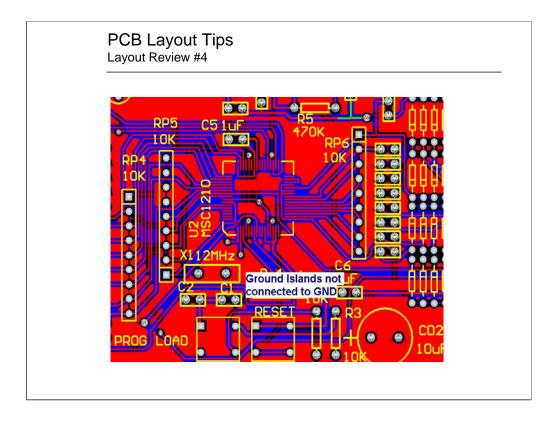
The ground current from U3 was routed to the ground point for the crystal (Y1) capacitors and then to the rest of the ground in the system. This caused a significant effect on the oscillator and made the clock very unstable.



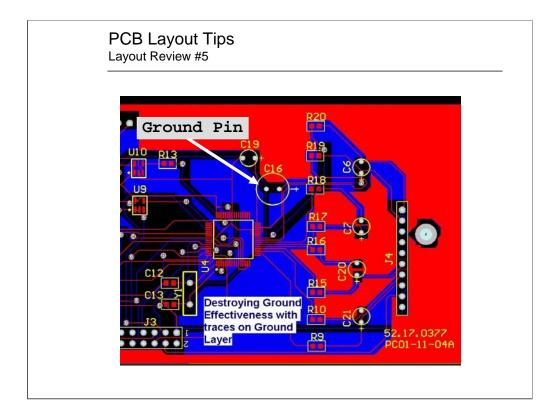
If we position capacitors and components with an order and goal of symmetry, the results could be unnecessary inductance and resistance that are introduced which will reduce the performance of the system.



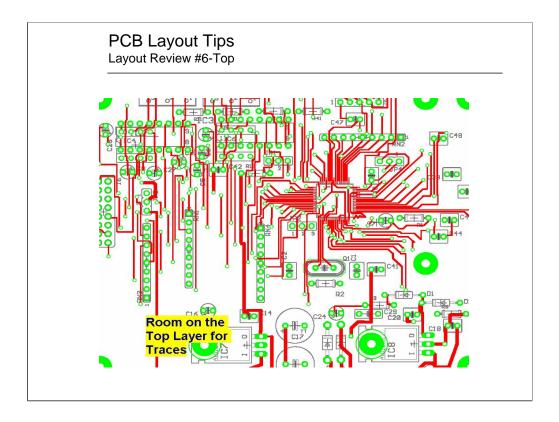
Here this board is designed with a reasonably solid ground plane and rather than connecting directly with feedthroughs to ground plane, there are large traces to a centralized ground connection point. The extra inductance and resistance, even with wide traces, will reduce the performance of the board compared to feedthroughs (or multiple feedthroughs) placed close to the component's ground connection.



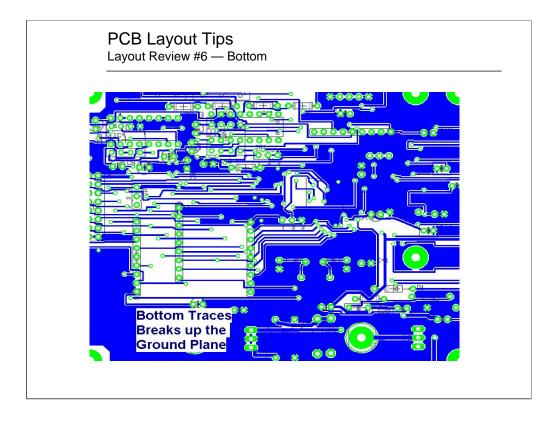
These top planes seem to be just an area fill for the gaps in the traces. When the plane areas on the top layer are not connected to the ground plane on the bottom, that means that the ground plane on the bottom doesn't have a continuous path available for current. If these top ground planes were connected to the bottom ground plane, the ground return currents would have a lower inductance path.



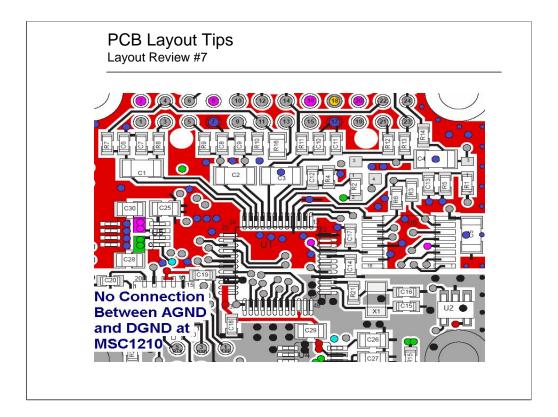
Here we see serious splits in the bottom ground plane. A close examination will also show that the traces that are splitting the ground plane are actually also ground signals.



As this layer is compared with the next slide, it is evident that some of the traces could have been put on this layer so that the ground layer could have been more solid.



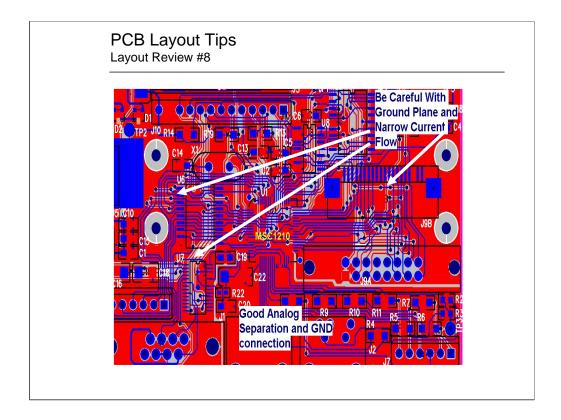
This shows the problem of using a digital PCB layout for an analog board. It simplifies the routing for most of the traces on each layer to go one direction, but that might lead to inefficiencies in the ground return currents and an unnecessary increase in inductance. Remember, inductance is defined by the size of the loop for the current.



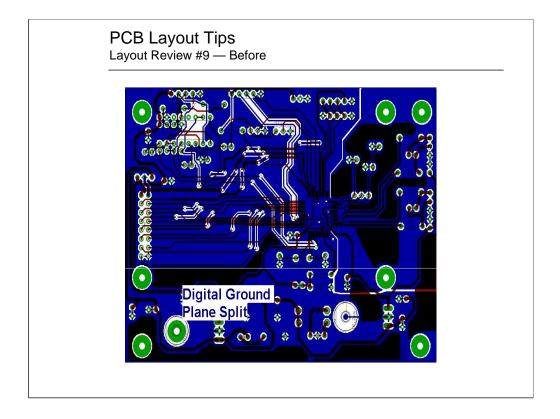
There is a good separation between the analog and digital sections, but the AGND and DGND should be connected together at the ADC.



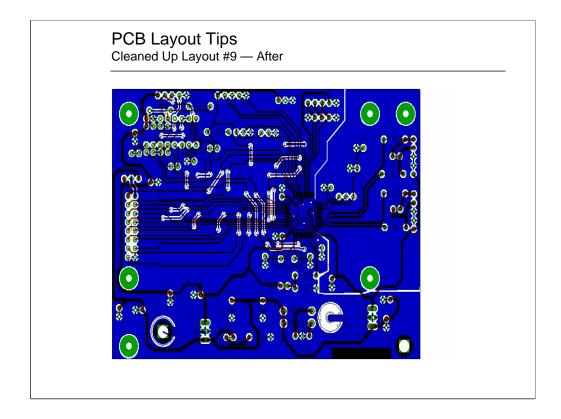
The goal was to place the resistor to protect the reset pin. The close placement of the resistor didn't solve the problem. However the feedthrough was to an external connector that defeated the purpose of the resistor.



The Analog and Digital sections are nicely separated. The AGND and DGND are connected with a wide connection right at the MSC1210. But the ground plane sometimes has narrow channels for current which will increase inductance and noise. The return currents for the digital signals will want to travel under the horizontal traces, but the channels in the ground plane are generally vertical.



Analog and Digital sections separated with ground planes on both the bottom and the top. But the bottom ground plane is seriously split so that the ground return currents can't flow close to the source signal wires.



A few simple changes in the routing were able to provide a much better ground return path. Larger continuous areas of ground plane translate into short return current paths and lower inductance.

PCB Layout Tips Summary
SUB Size

Higher resolution systems reveal PCB layout errors more clearly!

Basic PCB Design Principles

Separate analog and digital signals
Establish good grounding
Minimize inductance
Control thermocouples

PCB Layout Reviews

Learn from your mistakes!